

SOT844-1

plastic low profile fine-pitch ball grid array package; 183 balls; body 10 x 10 x 1.05 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA183
Package type industry code	LFBGA183
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	15-1-2004

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		9.9	-	10	10.1	mm
E	package width		9.9	-	10	10.1	mm
A	seated height		[tbd]	-	1.55	1.55	mm
A ₂	package height		0.95	-	1.05	1.2	mm
n ₂	actual quantity of termination		-	-	183	-	



2. Package outline

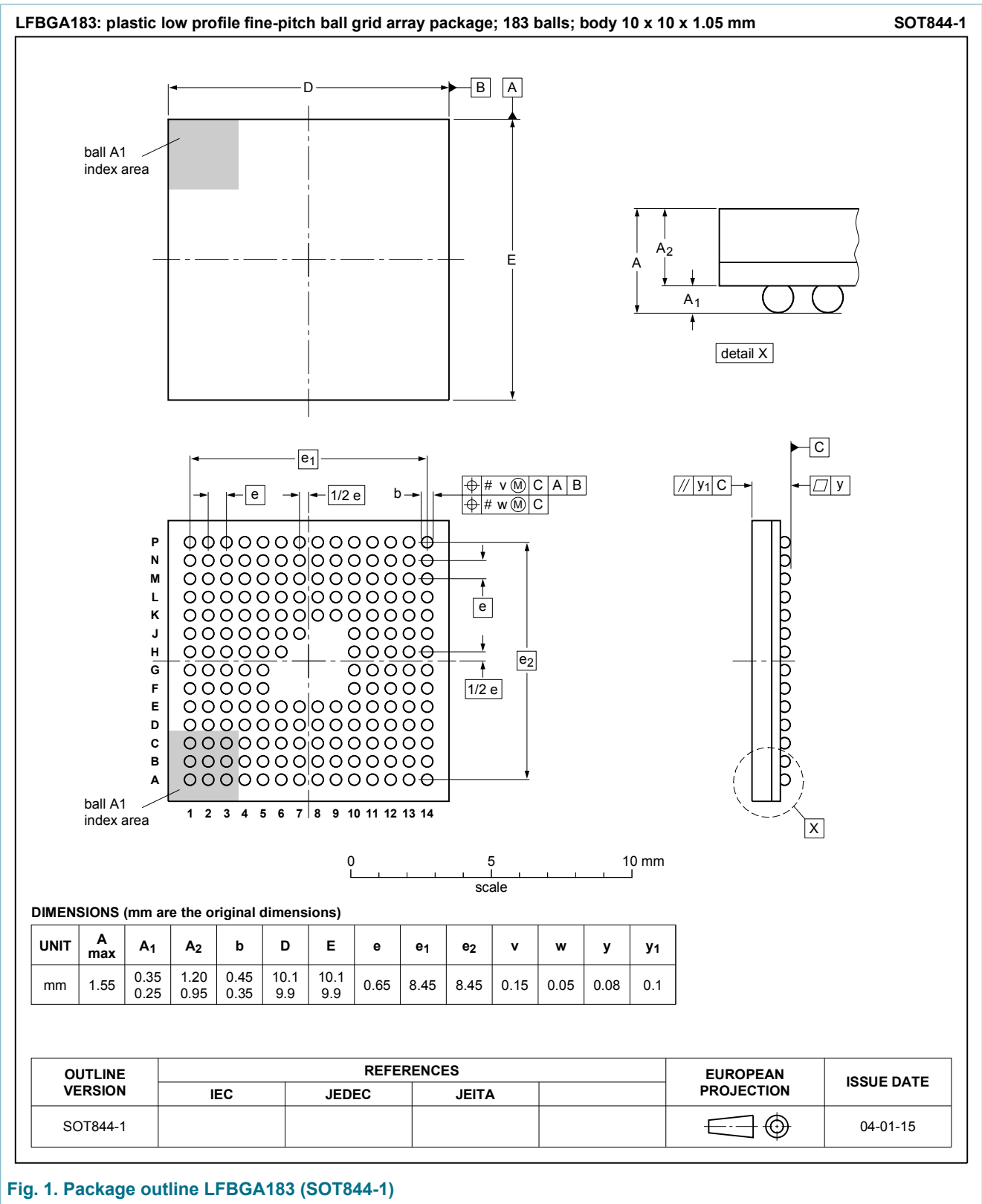


Fig. 1. Package outline LFBGA183 (SOT844-1)

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3. Soldering

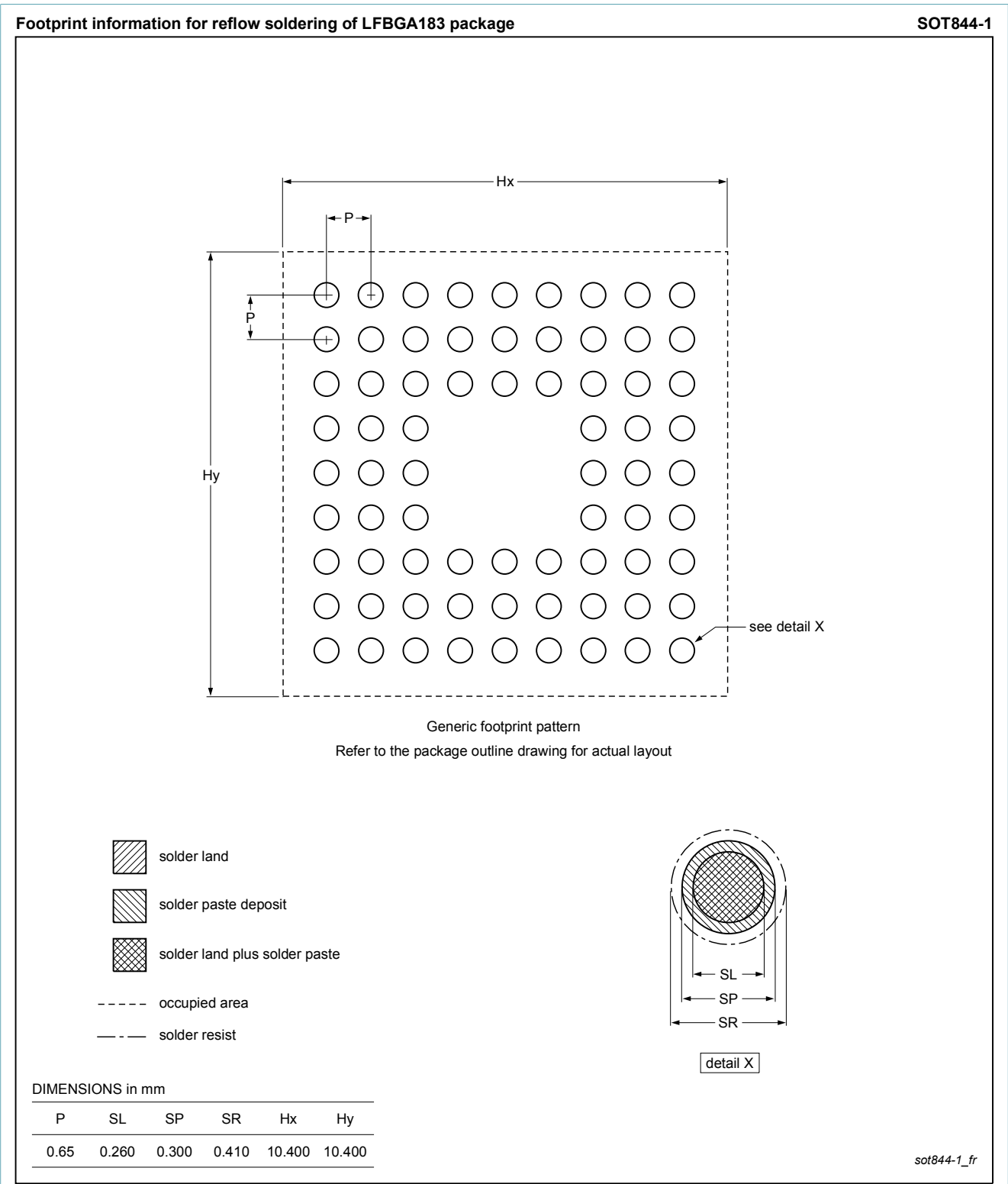


Fig. 2. Reflow soldering footprint for LFBGA183 (SOT844-1)

4. Legal information

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